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Understanding [Embedded - DSP \(Digital Signal Processors\)](#)

[Embedded - DSP \(Digital Signal Processors\)](#) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of [Embedded - DSP \(Digital Signal Processors\)](#)

Details

Product Status	Obsolete
Type	SC140 Core
Interface	Communications Processor Module (CPM)
Clock Rate	275MHz
Non-Volatile Memory	External
On-Chip RAM	512kB
Voltage - I/O	3.30V
Voltage - Core	1.60V
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	332-BFBGA, FCBGA
Supplier Device Package	332-FCBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/msc8103vt1100f

Target Applications

The MSC8103 targets applications requiring very high performance, very large amounts of internal memory, and such networking capabilities as:

- Third-generation wideband wireless infrastructure systems
- Packet Telephony systems
- Multi-channel modem banks
- Multi-channel xDSL

Product Documentation

The documents listed in **Table 1** are required for a complete description of the MSC8103 and are necessary to design properly with the part. Documentation is available from the following sources (see back cover for details):

- A local Freescale distributor
- A Freescale Semiconductor sales office
- A Freescale Semiconductor Literature Distribution Center
- The world wide web (WWW)

Table 1. MSC8103 Documentation

Name	Description	Order Number
<i>MSC8103 Technical Data</i>	MSC8103 features list and physical, electrical, timing, and package specifications	MSC8103/D
<i>MSC8101 User's Guide</i>	Detailed functional description of the MSC8101 memory configuration, operation, and register programming. All details apply to the MSC8103.	MSC8101UG/D
<i>MSC8103 Reference Manual</i>	Detailed description of the MSC8103 processor core and instruction set	MSC8103RM/D
<i>SC140 DSP Core Reference Manual</i>	Detailed description of the SC140 family processor core and instruction set	MNSC140CORE/D
<i>Application Notes</i>	Documents describing specific applications or optimized device operation including code examples	See the MSC8103 product website

Although there are eight interrupt request ($\overline{\text{IRQ}}$) connections to the core processor, there are multiple external lines that can connect to these internal signal lines. After reset, the default configuration includes two $\overline{\text{IRQ1}}$ and two $\overline{\text{IRQ7}}$ input lines. The designer must select one line for each required interrupt and reconfigure the other external signal line or lines for alternate functions.

Table 1-5. System Bus, HDI16, and Interrupt Signals

Signal	Data Flow	Description
A[0–31]	Input/Output	Address Bus When the MSC8103 is in external master bus mode, these pins function as the address bus. The MSC8103 drives the address of its internal bus masters and responds to addresses generated by external bus masters. When the MSC8103 is in Internal Master Bus mode, these pins are used as address lines connected to memory devices and are controlled by the MSC8103 memory controller.
TT[0–4]	Input/Output	Bus Transfer Type The bus master drives these pins during the address tenure to specify the type of transaction.
TSIZ[0–3]	Input/Output	Transfer Size The bus master drives these pins with a value indicating the number of bytes transferred in the current transaction.
$\overline{\text{TBS}}$	Input/Output	Bus Transfer Burst The bus master asserts this pin to indicate that the current transaction is a burst transaction (transfers four quad words).
$\overline{\text{IRQ1}}$	Input	Interrupt Request 1¹ One of eight external lines that can request a service routine, via the internal interrupt controller, from the SC140 core.
$\overline{\text{GBL}}$	Input/Output	Global¹ When a master within the chip initiates a bus transaction, it drives this pin. When an external master initiates a bus transaction, it should drive this pin. Assertion of this pin indicates that the transfer is global and it should be snooped by caches in the system.
Reserved	Output	The primary configuration is reserved.
BADDR29	Output	Burst Address 29¹ One of five outputs of the memory controller. These pins connect directly to memory devices controlled by the MSC8103 memory controller.
$\overline{\text{IRQ2}}$	Input	Interrupt Request 2¹ One of eight external lines that can request a service routine, via the internal interrupt controller, from the SC140 core.
Reserved	Output	The primary configuration is reserved.
BADDR30	Output	Burst Address 30¹ One of five outputs of the memory controller. These pins connect directly to memory devices controlled by the MSC8103 memory controller.
$\overline{\text{IRQ3}}$	Input	Interrupt Request 3¹ One of eight external lines that can request a service routine, via the internal interrupt controller, from the SC140 core.
Reserved	Output	The primary configuration is reserved.
BADDR31	Output	Burst Address 31¹ One of five outputs of the memory controller. These pins connect directly to memory devices controlled by the MSC8103 memory controller.
$\overline{\text{IRQ5}}$	Input	Interrupt Request 5¹ One of eight external lines that can request a service routine, via the internal interrupt controller, from the SC140 core.

Table 1-5. System Bus, HDI16, and Interrupt Signals (Continued)

Signal	Data Flow	Description
D[32–47]	Input/Output	Data Bus Bits 32–47 In write transactions the bus master drives the valid data on this bus. In read transactions the slave drives the valid data on this bus.
HD[0–15]	Input/Output	Host Data² When the HDI16 interface is enabled, these signals are lines 0-15 of the bidirectional tri-state data bus.
D[48–51]	Input/Output	Data Bus Bits 48–51 In write transactions the bus master drives the valid data on these pins. In read transactions the slave drives the valid data on these pins.
HA[0–3]	Input	Host Address Line 0–3³ When the HDI16 interface bus is enabled, these lines address internal host registers.
D52	Input/Output	Data Bus Bit 52 In write transactions the bus master drives the valid data on this pin. In read transactions the slave drives the valid data on this pin.
$\overline{\text{HCS1}}$	Input	Host Chip Select³ When the HDI16 interface is enabled, this is one of the two chip-select pins. The HDI16 chip select is a logical OR of $\overline{\text{HCS1}}$ and $\overline{\text{HCS2}}$.
D53	Input/Output	Data Bus Bit 53 In write transactions the bus master drives the valid data on this pin. In read transactions the slave drives the valid data on this pin.
HRW	Input	Host Read Write Select³ When the HDI16 interface is enabled in Single Strobe mode, this is the read/write input (HRW).
$\overline{\text{HRD}}/\text{HRD}$	Input	Host Read Strobe³ When the HDI16 is programmed to interface with a double data strobe host bus, this pin is the read data strobe Schmitt trigger input ($\overline{\text{HRD}}/\text{HRD}$). The polarity of the data strobe is programmable.
D54	Input/Output	Data Bus Bit 54 In write transactions the bus master drives the valid data on this pin. In read transactions the slave drives the valid data on this pin.
$\overline{\text{HDS}}/\text{HDS}$	Input	Host Data Strobe³ When the HDI16 is programmed to interface with a single data strobe host bus, this pin is the data strobe Schmitt trigger input ($\overline{\text{HDS}}/\text{HDS}$). The polarity of the data strobe is programmable.
$\overline{\text{HWR}}/\text{HWR}$	Input	Host Write Data Strobe³ When the HDI16 is programmed to interface with a double data strobe host bus, this pin is the write data strobe Schmitt trigger input ($\overline{\text{HWR}}/\text{HWR}$). The polarity of the data strobe is programmable.
D55	Input/Output	Data Bus Bit 55 In write transactions the bus master drives the valid data on this pin. In read transactions the slave drives the valid data on this pin.
$\overline{\text{HREQ}}/\text{HREQ}$	Output	Host Request³ When the HDI16 is programmed to interface with a single host request host bus, this pin is the host request output ($\overline{\text{HREQ}}/\text{HREQ}$). The polarity of the host request is programmable. The host request may be programmed as a driven or open-drain output.
$\overline{\text{HTRQ}}/\text{HTRQ}$	Output	Transmit Host Request³ When the HDI16 is programmed to interface with a double host request host bus, this pin is the transmit host request output ($\overline{\text{HTRQ}}/\text{HTRQ}$). The signal can be programmed as driven or open drain. The polarity of the host request is programmable.

Table 1-5. System Bus, HDI16, and Interrupt Signals (Continued)

Signal	Data Flow	Description
$\overline{\text{IRQ5}}$	Input	Interrupt Request 5¹ One of eight external lines that can request a service routine, via the internal interrupt controller, from the SC140 core.
DP5	Input/Output	Data Parity 5¹ The agent that drives the data bus also drives the data parity signals. The value driven on the data parity five pin should give odd parity (odd number of ones) on the group of signals that includes data parity 5 and D[40–47].
DREQ4	Input	DMA Request 4¹ An external peripheral uses this pin to request DMA service.
$\overline{\text{EXT_DBG3}}$	Output	External Data Bus Grant 3^{1,2} The MSC8103 asserts this pin to grant data bus ownership to an external bus master.
$\overline{\text{IRQ6}}$	Input	Interrupt Request 6¹ One of eight external lines that can request a service routine, via the internal interrupt controller, from the SC140 core.
DP6	Input/Output	Data Parity 6¹ The agent that drives the data bus also drives the data parity signals. The value driven on the data parity six pin should give odd parity (odd number of ones) on the group of signals that includes data parity 6 and D[48–55].
$\overline{\text{DACK3}}$	Output	DMA Acknowledge 3¹ The DMA controller drives this output to acknowledge the DMA transaction on the bus.
$\overline{\text{IRQ7}}$	Input	Interrupt Request 7¹ One of eight external lines that can request a service routine, via the internal interrupt controller, from the SC140 core.
DP7	Input/Output	Data Parity 7¹ The master or slave that drives the data bus also drives the data parity signals. The value driven on the data parity seven pin should give odd parity (odd number of ones) on the group of signals that includes data parity 7 and D[56–63].
$\overline{\text{DACK4}}$	Output	DMA Acknowledge¹ The DMA controller drives this output to acknowledge the DMA transaction on the bus.
$\overline{\text{TA}}$	Input/Output	Transfer Acknowledge Indicates that a data beat is valid on the data bus. For single beat transfers, assertion of $\overline{\text{TA}}$ indicates the termination of the transfer. For burst transfers, $\overline{\text{TA}}$ is asserted four times to indicate the transfer of four data beats with the last assertion indicating the termination of the burst transfer.
$\overline{\text{TEA}}$	Input/Output	Transfer Error Acknowledge Indicates a bus error. masters within the MSC8103 monitor the state of this pin. The MSC8103 internal bus monitor can assert this pin if it identifies a bus transfer that is hung.
$\overline{\text{NMI}}$	Input	Non-Maskable Interrupt When an external device asserts this line, the MSC8103 $\overline{\text{NMI}}$ input is asserted.
$\overline{\text{NMI_OUT}}$	Output	Non-Maskable Interrupt Driven from the MSC8103 internal interrupt controller. Assertion of this output indicates that a non-maskable interrupt, pending in the MSC8103 internal interrupt controller, is waiting to be handled by an external host.
$\overline{\text{PSDVAL}}$	Input/Output	Data Valid Indicates that a data beat is valid on the data bus. The difference between the $\overline{\text{TA}}$ pin and $\overline{\text{PSDVAL}}$ is that the $\overline{\text{TA}}$ pin is asserted to indicate data transfer terminations while the $\overline{\text{PSDVAL}}$ signal is asserted with each data beat movement. Thus, when $\overline{\text{TA}}$ is asserted, $\overline{\text{PSDVAL}}$ is asserted, but when $\overline{\text{PSDVAL}}$ is asserted, $\overline{\text{TA}}$ is not necessarily asserted. For example when the SDMA initiates a double word (2x64 bits) transfer to a memory device that has a 32-bit port size, $\overline{\text{PSDVAL}}$ is asserted three times without $\overline{\text{TA}}$, and finally both pins are asserted to terminate the transfer.

Table 1-7. Port A Signals (Continued)

Name		Dedicated I/O Data Direction	Description
General-Purpose I/O	Peripheral Controller: Dedicated Signal Protocol		
PA17	FCC1: RXD7 <i>UTOPIA</i>	Input	FCC1: UTOPIA Receive Data Bit 7. The MSC8103 inputs ATM cell octets (UTOPIA interface data) on RXD[0–7]. RXD7 is the most significant bit. When no ATM data is available, idle cells are inserted. A cell is 53 bytes. To support Multi-PHY configurations, RXD[0–7] is tri-stated, enabled only when RXENB is asserted.
	FCC1: RXD0 <i>MII and HDLC nibble</i>	Input	FCC1: MII and HDLC Nibble Receive Data Bit 0 RXD[3–0] is supported by MII and HDLC nibble mode in FCC1. RXD0 is the least significant bit.
	FCC1: RXD <i>HDLC serial and transparent</i>	Input	FCC1: HDLC Serial and Transparent Receive Data Bit This is the single receive data bit supported by HDLC and transparent modes.
PA16	FCC1: RXD6 <i>UTOPIA</i>	Input	FCC1: UTOPIA Receive Data Bit 6. The MSC8103 inputs ATM cell octets (UTOPIA interface data) on RXD[0–7]. This is bit 6 of the receive data. RXD7 is the most significant bit. When no ATM data is available, idle cells are inserted. A cell is 53 bytes. To support Multi-PHY configurations, RXD[0–7] is tri-stated, enabled only when RXENB is asserted.
	FCC1: RXD1 <i>MII and HDLC nibble</i>	Input	FCC1: MII and HDLC Nibble Receive Data Bit 1 This is bit 1 of the receive nibble data. RXD3 is the most significant bit.
PA15	FCC1: RXD5 <i>UTOPIA</i>	Input	FCC1: UTOPIA Receive Data Bit 5 The MSC8103 inputs ATM cell octets (UTOPIA interface data) on RXD[0–7]. This is bit 5 of the receive data. RXD7 is the most significant bit. When no ATM data is available, idle cells are inserted. A cell is 53 bytes. To support Multi-PHY configurations, RXD[0–7] is tri-stated, enabled only when RXENB is asserted.
	RXD2 <i>MII and HDLC nibble</i>	Input	FCC1: MII and HDLC Nibble Receive Data Bit 2 This is bit 2 of the receive nibble data. RXD3 is the most significant bit.
PA14	FCC1: RXD4 <i>UTOPIA</i>	Input	FCC1: UTOPIA Receive Data Bit 4. The MSC8103 inputs ATM cell octets (UTOPIA interface data) on RXD[0–7]. RXD7 is the most significant bit. RXD0 is the least significant bit. When no ATM data is available, idle cells are inserted. A cell is 53 bytes. To support Multi-PHY configurations, RXD[0–7] is tri-stated, enabled only when RXENB is asserted.
	FCC1: RXD3 <i>MII and HDLC nibble</i>	Input	FCC1: MII and HDLC Nibble Receive Data Bit 3 RXD3 is the most significant bit of the receive nibble bit.
PA13	FCC1: RXD3 <i>UTOPIA</i>	Input	FCC1: UTOPIA Receive Data Bit 3 The MSC8103 inputs ATM cell octets (UTOPIA interface data) on RXD[0–7]. RXD7 is the most significant bit. RXD0 is the least significant bit. A cell is 53 bytes. To support Multi-PHY configurations, RXD[0–7] is tri-stated, enabled only when RXENB is asserted.
	SDMA: MSNUM2	Output	Module Serial Number Bit 2 The MSNUM has 6 bits that identify devices using the serial DMA (SDMA) modules. MSNUM[0–4] is the sub-block code of the current peripheral controller using SDMA. MSNUM5 indicates the section, transmit (0) or receive (1), that is active during the transfer. The information is recorded in the SDMA transfer error registers.

Table 1-8. Port B Signals (Continued)

Name		Dedicated I/O Data Direction	Description
General-Purpose I/O	Peripheral Controller: Dedicated I/O Protocol		
PB28	FCC2: $\overline{\text{RTS}}$ <i>HDLC serial, HDLC nibble, and transparent</i>	Output	FCC2: Request to Send One of the standard modem interface signals supported by FCC2 ($\overline{\text{RTS}}$, $\overline{\text{CTS}}$, and $\overline{\text{CD}}$). $\overline{\text{RTS}}$ is asynchronous with the data. $\overline{\text{RTS}}$ is typically used in conjunction with $\overline{\text{CD}}$. The MSC8103 FCC2 transmitter requests the receiver to send data by asserting $\overline{\text{RTS}}$ low. The request is accepted when $\overline{\text{CTS}}$ is returned low.
	FCC2: RX_ER <i>MII</i>	Input	FCC2: Media Independent Interface Receive Error Asserted by an external fast Ethernet PHY to indicate a receive error, which often indicates bad wiring.
	SCC2: $\overline{\text{RTS}}$, TENA	Output	SCC2: Request to Send, Transmit Enable Typically used in conjunction with $\overline{\text{CD}}$ supported by SCC2. The MSC8103 SCC2 transmitter requests the receiver to send data by asserting $\overline{\text{RTS}}$ low. The request is accepted when $\overline{\text{CTS}}$ is returned low. TENA is the signal used in Ethernet mode.
	SI2 TDMB2: L1TSYNC <i>TDM serial</i>	Input	Time-Division Multiplexing B2: Layer 1 Transmit Synchronization The synchronizing signal for the transmit channel. See the serial interface with time-slot assigner chapter in the <i>MSC8103 Reference Manual</i> .
PB27	FCC2: COL <i>MII</i>	Input	FCC2: Media Independent Interface Collision Detect Asserted by an external fast Ethernet PHY when a collision is detected.
	SI2 TDMC2: L1TXD <i>TDM serial</i>	Output	Time-Division Multiplexing C2: Layer 1 Transmit Data TDMC2 transmits serial data out of L1TXD.
PB26	FCC2: CRS <i>MII</i>	Input	FCC2: Media Independent Interface Carrier Sense Input Asserted by an external fast Ethernet PHY to indicate activity on the cable.
	SI2 TDMC2: L1RXD <i>TDM serial</i>	Input	Time-Division Multiplexing C2: Layer 1 Receive Data TDMC2 receives serial data from L1RXD.
PB25	FCC2: TXD3 <i>MII and HDLC nibble</i>	Output	FCC2: MII and HDLC Nibble Transmit Data Bit 3 TXD3 is bit 3 and the most significant bit of the transmit data nibble.
	SI1 TDMA1: L1TXD3 <i>TDM nibble</i>	Output	Time-Division Multiplexing A1: Nibble Layer 1 Transmit Data Bit 3 L1TXD3 is bit 3 and the most significant bit of the transmit data nibble.
	SI2 TDMC2: L1TSYNC <i>TDM serial</i>	Input	Time-Division Multiplexing C2: Layer 1 Transmit Synchronization The synchronizing signal for the transmit channel. See the <i>Serial Interface with Time-Slot Assigner</i> chapter in the <i>MSC8103 Reference Manual</i> .
PB24	FCC2: TXD2 <i>MII and HDLC nibble</i>	Output	FCC2: MII and HDLC Nibble: Transmit Data Bit 2 TXD2 is bit 2 of the transmit data nibble.
	SI1 TDMA1: L1RXD3 <i>nibble</i>	Input	Time-Division Multiplexing A1: Nibble Layer 1 Receive Data Bit 3 L1RXD3 is bit 3 and the most significant bit of the receive data nibble.
	SI2 TDMC2: L1RSYNC <i>serial</i>	Input	Time-Division Multiplexing C2: Layer 1 Receive Synchronization The synchronizing signal for the receive channel.

Table 1-9. Port C Signals (Continued)

Name		Dedicated I/O Data Direction	Description
General-Purpose I/O	Peripheral Controller: Dedicated I/O Protocol		
PC22	SI1: L1ST1	Output	Serial Interface 1: Layer 1 Strobe 1 The MSC8103 time-slot assigner supports up to four strobe outputs that can be asserted on a bit or byte basis. The strobe outputs are useful for interfacing to other devices that do not support the multiplexed interface or for enabling/disabling three-state I/O buffers in a multiple-transmitter architecture. These strobes can also generate output wave forms for such applications as stepper-motor control.
	CLK10	Input	Clock 10 The CPM supports up to 10 clock input pins sent to the bank-of-clocks selection logic, where they can be routed to the controllers.
	DMA: DREQ1	Input/ Output	DMA: Request 1 <u>DACK1</u> , <u>DREQ1</u> , <u>DRACK1</u> , and <u>DONE1</u> belong to the SIU DMA controller. <u>DONE1</u> and <u>DRACK1</u> are signals on the same pin and therefore cannot be used simultaneously. There are two sets of DMA pins associated with the PIO ports.
PC15	SMC2: SMTXD	Output	SMC2: Serial Management Transmit Data The SMC interface consists of SMTXD, SMRXD, <u>SMSYN</u> , and a clock. Not all signals are used for all applications. SMCs are full-duplex ports that support three protocols or modes: UART, transparent, or general-circuit interface (GCI). See also PA9.
	SCC1: <u>CTS</u> / <u>CLSN</u>	Input	SCC1: Clear To Send, Collision Typically used in conjunction with <u>RTS</u> . The MSC8103 SCC1 transmitter sends out a request to send data signal (<u>RTS</u>). The request is accepted when <u>CTS</u> is returned low. <u>CLSN</u> is the signal used in Ethernet mode. See also PC29.
	FCC1: TXADDR0 <i>UTOPIA master</i>	Output	FCC1: UTOPIA Master Transmit Address Bit 0 This is master transmit address bit 0.
	FCC1: TXADDR0 <i>UTOPIA slave</i>	Input	FCC1: UTOPIA Slave Transmit Address Bit 0 This is slave transmit address bit 0.
PC14	SI1: L1ST2	Output	Serial Interface 1: Layer 1 Strobe 2 The MSC8103 time-slot assigner supports up to four strobe outputs that can be asserted on a bit or byte basis. The strobe outputs are useful for interfacing to other devices that do not support the multiplexed interface or for enabling/disabling three-state I/O buffers in a multiple-transmitter architecture. These strobes can also be generate output wave forms for such applications as stepper-motor control.
	SCC1: <u>CD</u> , <u>RENA</u>	Input	SCC1: Carrier Detect, Receive Enable Typically used in conjunction with <u>RTS</u> supported by SCC1. The MSC8103MSC8103 SCC1 transmitter requests the receiver to send data by asserting <u>RTS</u> low. The request is accepted when <u>CTS</u> is returned low.
	FCC1: RXADDR0 <i>UTOPIA master</i>	Output	FCC1: UTOPIA Multi-PHY Master Receive Address Bit 0 This is master receive address bit 0.
	FCC1: RXADDR0 <i>UTOPIA slave</i>	Input	FCC1: UTOPIA Multi-PHY Slave Receive Address Bit 0 This is slave receive address bit 0.

Table 1-10. Port D Signals (Continued)

Name		Dedicated I/O Data Direction	Description
General-Purpose I/O	Peripheral Controller: Dedicated I/O Protocol		
PD19	FCC1: TXADDR4 <i>UTOPIA master</i>	Output	FCC1: Multi-PHY Master Transmit Address Bit 4 Multiplexed Polling This is master transmit address bit 4.
	FCC1: TXADDR4 <i>UTOPIA slave</i>	Input	FCC1: UTOPIA Slave Transmit Address Bit 4 This is slave transmit address bit 4.
	FCC1: TXCLAV3 <i>UTOPIA multi-PHY master, direct polling</i>	Input	FCC1: UTOPIA Multi-PHY master Transmit Cell Available 3 Direct Polling Asserted by an external UTOPIA slave PHY to indicate that it can accept one complete ATM cell.
	BRG10	Output	Baud Rate Generator 1 Output The CPM supports up to 8 BRGs for use internally by the bank-of-clocks selection logic and/or to provide an output to one of the 8 BRG pins. BRG10 can be the internal input to the SIU timers. When CLK5 is selected (see PC27 above), it is the source for BRG10 which is the default input for the SIU timers. See the system interface unit (SIU) chapter in the <i>MSC8103 Reference Manual</i> for additional information. If CLK5 is not enabled, BRG10 uses an internal input. If TMCLK is enabled (see PC26 above), the BRG10 input to the SIU timers is disabled.
	SPI: $\overline{\text{SPISEL}}$	Input	SPI: Select The SPI interface comprises four signals: master out slave in (SPIMOSI), master in slave out (SPIMISO), clock (SPICLK) and select (SPISEL). The SPI can be configured as a slave or master in single- or multiple-master environments. $\overline{\text{SPISEL}}$ is the enable input to the SPI slave. In a multimaster environment, SPISEL (always an input) detects an error when more than one master is operating. SPI masters must output a slave select signal to enable SPI slave devices by using a separate general-purpose I/O signal. Assertion of an SPI SPISEL while it is master causes an error.
PD18	FCC1: RXADDR4 <i>UTOPIA master</i>	Output	FCC1: UTOPIA Master Receive Address Bit 4 This is master receive address bit 4.
	FCC1: RXADDR4 <i>UTOPIA slave</i>	Input	FCC1: UTOPIA Slave Receive Address Bit 4 This is slave receive address bit 4.
	FCC1: RXCLAV3 <i>UTOPIA multi-PHY master, direct polling</i>	Input	FCC1: UTOPIA Multi-PHY Master Receive Cell Available 3 Direct Polling Asserted by an external PHY when one complete ATM cell is available for transfer.
	SPI: SPICLK	Input/ Output	SPI: Clock The SPI interface comprises four signals: master out slave in (SPIMOSI), master in slave out (SPIMISO), clock (SPICLK) and select (SPISEL). The SPI can be configured as a slave or master in single- or multiple-master environments. SPICLK is a gated clock, active only during data transfers. Four combinations of SPICLK phase and polarity can be configured. When the SPI is a master, SPICLK is the clock output signal that shifts received data in from SPIMISO and transmitted data out to SPIMOSI.

Physical and Electrical Specifications 2

This document contains detailed information on environmental limits, power considerations, DC/AC electrical characteristics, and AC timing specifications for the MSC8103 communications processor, mask set 2K87M. For additional information, see the *MSC8103 Reference Manual*.

2.1 Absolute Maximum Ratings

CAUTION

This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, normal precautions should be taken to avoid exceeding maximum voltage ratings. Reliability is enhanced if unused inputs are tied to an appropriate logic voltage level (for example, either GND or V_{CC}).

In calculating timing requirements, adding a maximum value of one specification to a minimum value of another specification does not yield a reasonable sum. A maximum specification is calculated using a worst case variation of process parameter values in one direction. The minimum specification is calculated using the worst case for the same parameters in the opposite direction. Therefore, a “maximum” value for a specification never occurs in the same device with a “minimum” value for another specification; adding a maximum to a minimum represents a condition that can never exist. **Table 2-1** describes the maximum electrical ratings for the MSC8103.

Table 2-1. Absolute Maximum Ratings²

Rating	Symbol	Value	Unit
Core supply voltage ³	V_{DD}	–0.2 to 1.7	V
PLL supply voltage ³	V_{CCSYN}	–0.2 to 1.7	V
I/O supply voltage ³	V_{DDH}	–0.2 to 3.6	V
Input voltage ³	V_{IN}	(GND – 0.2) to 3.6	V
Maximum operating temperature range ⁴	T_J	–40 to 120	°C
Storage temperature range	T_{STG}	–55 to +150	°C
Notes: <ol style="list-style-type: none"> Functional operating conditions are given in Table 2-2. Absolute maximum ratings are stress ratings only, and functional operation at the maximum is not guaranteed. Stress beyond the listed limits may affect device reliability or cause permanent damage. The input voltage must not exceed the I/O supply V_{DDH} by more than 2.5 V at any time, including during power-on reset. In turn, V_{DDH} can exceed V_{DD}/V_{CCSYN} by more than 3.3 V during power-on reset, but for no more than 100 ms. V_{DDH} should not exceed V_{DD}/V_{CCSYN} by more than 2.1 V during normal operation. V_{DD}/V_{CCSYN} must not exceed V_{DDH} by more than 0.4 V at any time, including during power-on reset. See Section 4.2, Electrical Design Considerations, on page 4-1 for more information. Section 4.1, Thermal Design Considerations, on page 4-1 includes a formula for computing the chip junction temperature (T_J). 			

Table 2-11. Clock Ranges

Clock	Symbol	Maximum Rated Core Frequency		
		All	Max. Values for SC140 Clock Rating of:	
		Min	275 MHz	300 MHz
Input Clock	CLKIN	18 MHz	91.67 MHz	100 MHz
SPLL MF Clock	SPLLMFCLK	18 MHz	34.38 MHz	37.5 MHz
Bus/Output	BCLK CLKOUT	18 MHz	91.67 MHz	100 MHz
Serial Communications Controller	SCLK	35 MHz	91.67 MHz	100 MHz
Communications Processor Module	CPMCLK	70 MHz	183.3 MHz	200 MHz
SC140 Core	DSPCLK	72 MHz	275 MHz	300 MHz
Baud Rate Generator <ul style="list-style-type: none"> For BRG DF = 4 For BRG DF = 16 (default) For BRG DF = 64 For BRG DF = 256 	BRGCLK	36 MHz 9 MHz 2.25 MHz 562.5 KHz	91.67 MHz 22.91 MHz 5.73 MHz 1.43 MHz	100 MHz 25 MHz 6.25 MHz 1.56 MHz

2.6.4 Reset Timing

The MSC8103 has several inputs to the reset logic:

- Power-on reset ($\overline{\text{PORESET}}$)
- External hard reset ($\overline{\text{HRESET}}$)
- External soft reset ($\overline{\text{SRESET}}$)

Asserting an external $\overline{\text{PORESET}}$ causes concurrent assertion of an internal $\overline{\text{PORESET}}$ signal, $\overline{\text{HRESET}}$, and $\overline{\text{SRESET}}$. When the external $\overline{\text{PORESET}}$ signal is deasserted, the MSC8103 samples several configuration pins:

- $\overline{\text{RSTCONF}}$ —determines whether the MSC8103 is a master (0) or slave (1) device
- DBREQ—determines whether to operate in normal mode (0) or invoke the SC140 debug mode (1)
- HPE—disable (0) or enable (1) the host port (HDI16)
- BTM[0–1]—boot from external memory (00) or the HDI16 (01)

All these reset sources are fed into the reset controller, which takes different actions depending on the source of the reset. The reset status register indicates the last sources to cause a reset. **Table 2-12** describes reset causes.

Table 2-12. Reset Causes

Name	Direction	Description
Power-on reset ($\overline{\text{PORESET}}$)	Input	$\overline{\text{PORESET}}$ initiates the power-on reset flow that resets all the MSC8103s and configures various attributes of the MSC8103, including its clock mode.
Hard reset ($\overline{\text{HRESET}}$)	Input/Output	The MSC8103 can detect an external assertion of $\overline{\text{HRESET}}$ only if it occurs while the MSC8103 is not asserting reset. During $\overline{\text{HRESET}}$, $\overline{\text{SRESET}}$ is asserted. $\overline{\text{HRESET}}$ is an open-drain pin.
Soft reset ($\overline{\text{SRESET}}$)	Input/Output	The MSC8103 can detect an external assertion of $\overline{\text{SRESET}}$ only if it occurs while the MSC8103 is not asserting reset. $\overline{\text{SRESET}}$ is an open-drain pin.

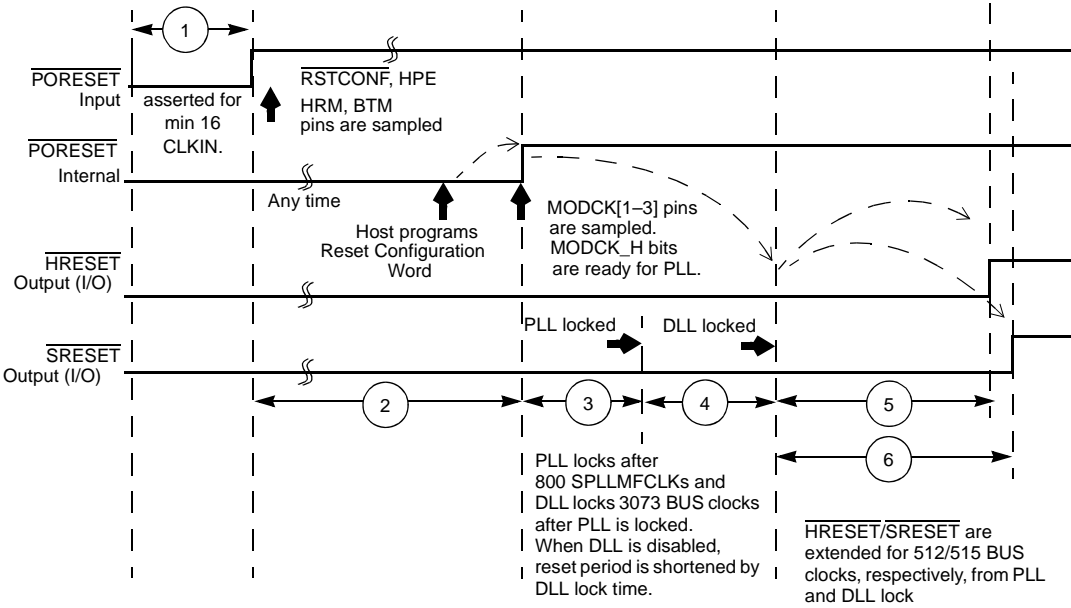


Figure 2-7. Host Reset Configuration Timing

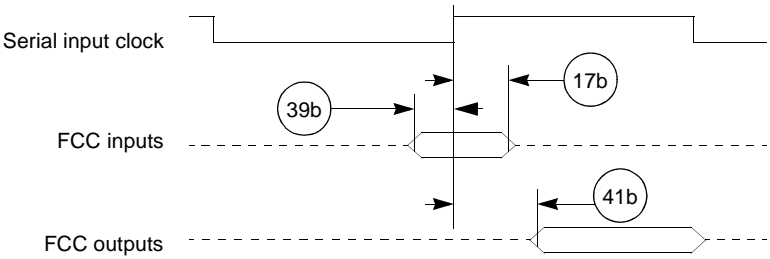


Figure 2-19. FCC External Clock Diagram

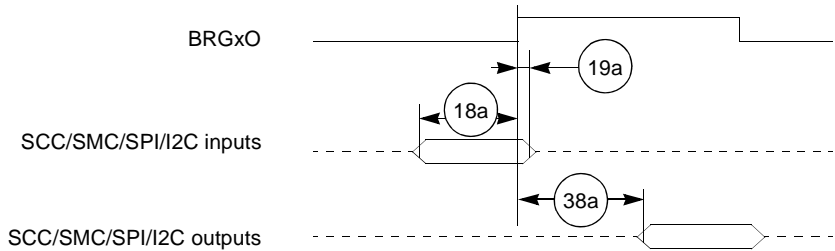


Figure 2-20. SCC/SMC/SPI/I²C Internal Clock Diagram

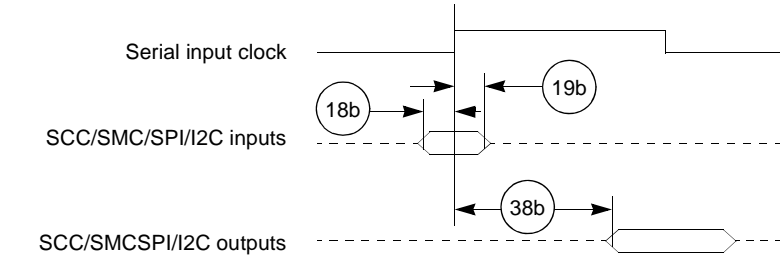


Figure 2-21. SCC/SMC/SPI/I²C External Clock Diagram

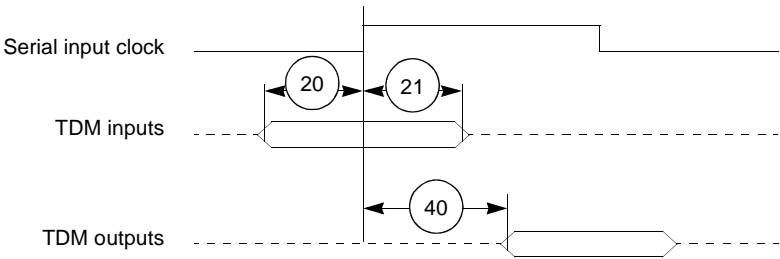


Figure 2-22. TDM Signal Diagram

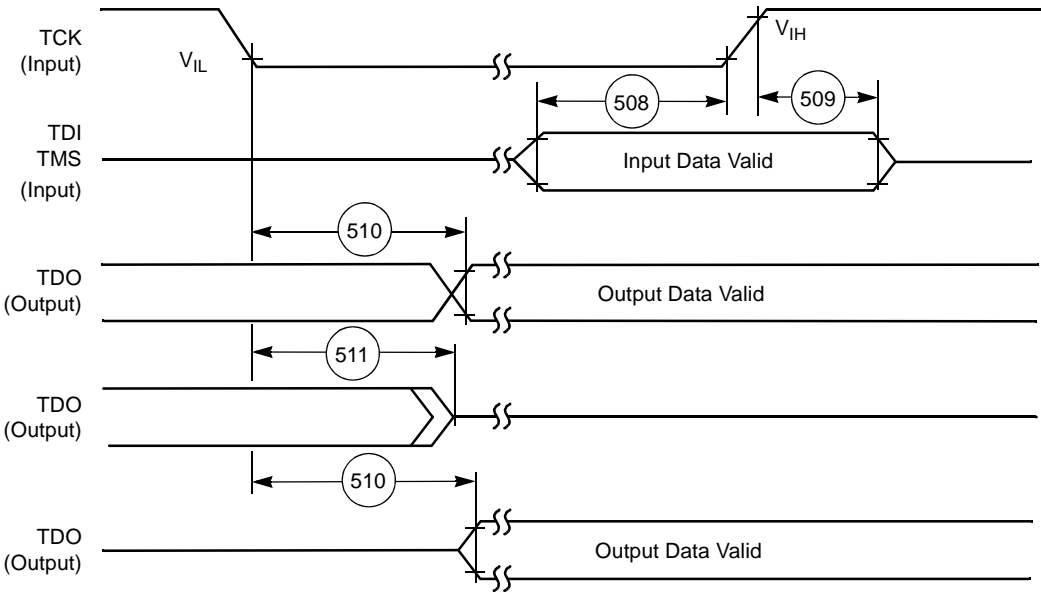


Figure 2-25. Test Access Port Timing Diagram

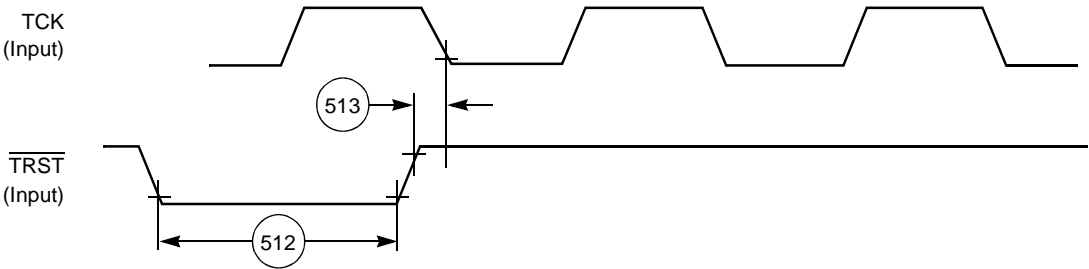


Figure 2-26. $\overline{\text{TRST}}$ Timing Diagram

Table 3-1. MSC8103 Signal Listing By Name (Continued)

Signal Name	Number
D42	A12
D43	D13
D44	C13
D45	B13
D46	A13
D47	E14
D48	D14
D49	C14
D50	B14
D51	A14
D52	D15
D53	C15
D54	B15
D55	A15
D56	E16
D57	D16
D58	C16
D59	B16
D60	A16
D61	C17
D62	A17
D63	A18
$\overline{\text{DACK1}}$	N5
$\overline{\text{DACK2}}$	N1
$\overline{\text{DACK3}}$	D5
$\overline{\text{DACK4}}$	F6
$\overline{\text{DBB}}$	C18
$\overline{\text{DBG}}$	B18
DBREQ	D2
DLLIN	P8
DP0	C2
DP1	B1
DP2	D4
DP3	B2

Table 3-1. MSC8103 Signal Listing By Name (Continued)

Signal Name	Number
PA18	W2
PA19	R5
PA20	T3
PA21	U1
PA22	R3
PA23	P4
PA24	P2
PA25	N2
PA26	M6
PA27	L1
PA28	K1
PA29	J1
PA30	J7
PA31	G1
PB18	R4
PB19	U2
PB20	P5
PB21	T1
PB22	T2
PB23	V1
PB24	P3
PB25	N3
PB26	M3
PB27	M1
PB28	L2
PB29	K4
PB30	H1
PB31	H4
$\overline{\text{PBS0}}$	K18
$\overline{\text{PBS1}}$	K17
$\overline{\text{PBS2}}$	K14
$\overline{\text{PBS3}}$	J19
$\overline{\text{PBS4}}$	H19
$\overline{\text{PBS5}}$	D17

Table 3-2. MSC8103 Signal Listing by Pin Designator (Continued)

Number	Signal Name
C4	D2
C5	D5
C6	D9
C7	D15
C8	D20
C9	D25
C10	D30
C11	D35 / HD3
C12	D40 / HD8
C13	D44 / HD12
C14	D49 / HA1
C15	D53 / HRW / $\overline{\text{HRD}}$
C16	D58 / HDDS
C17	D61
C18	$\overline{\text{DBB}}$ / $\overline{\text{IRQ3}}$
C19	BADDR29 / $\overline{\text{IRQ2}}$
D1	HPE / EE1
D2	DBREQ / EE0
D3	THERM2
D4	$\overline{\text{IRQ2}}$ / DP2 / $\overline{\text{EXT_DBG2}}$
D5	$\overline{\text{IRQ6}}$ / DP6 / $\overline{\text{DACK3}}$
D6	D8
D7	D14
D8	D19
D9	D24
D10	D29
D11	D34 / HD2
D12	D39 / HD7
D13	D43 / HD11
D14	D48 / HA0
D15	D52 / $\overline{\text{HCS1}}$
D16	D57 / HDSP
D17	$\overline{\text{PWE5}}$ / $\overline{\text{PSDDQM5}}$ / $\overline{\text{PBS5}}$
D18	$\overline{\text{IRQ1}}$ / $\overline{\text{GBL}}$
D19	BADDR27
E1	BTM0 / EE4
E2	EE3
E3	EE2
E4	V_{DDH}

Table 3-2. MSC8103 Signal Listing by Pin Designator (Continued)

Number	Signal Name
G6	GND
G7	D12
G8	GND
G9	D23
G10	GND
G11	D33 / HD1
G12	GND
G13	$\overline{\text{PSDVAL}}$
G14	GND
G15	V_{DDH}
G16	V_{DDH}
G17	$\overline{\text{TEA}}$
G18	MODCK3 / TC2 / BNKSEL2
G19	$\overline{\text{POE}}$ / $\overline{\text{PSDRAS}}$ / PGPL2
H1	PB30 / FCC2:MII:RX_DV / SCC2:TXD / TDBM2:L1RXD
H2	PD31 / SCC1:RXD / $\overline{\text{DRACK1}}$ / $\overline{\text{DONE1}}$
H3	PC31 / BRG10 / CLK1 / $\overline{\text{TGATE1}}$
H4	PB31 / FCC2:MII:TX_ER / SCC2:RXD / TDMB2:L1TXD
H5	GND
H6	TDI
H7	GND
H13	Reserved / BADDR31 / $\overline{\text{IRQ5}}$
H14	Reserved / BADDR30 / $\overline{\text{IRQ3}}$
H15	GND
H16	V_{DD}
H17	$\overline{\text{BR}}$
H18	ALE
H19	$\overline{\text{PWE4}}$ / $\overline{\text{PSDDQM4}}$ / $\overline{\text{PBS4}}$
J1	PA29 / FCC1:UTOP1A8:TXSOC / FCC1:MII:TX_ER
J2	PD30 / SCC1:TXD / DMA: $\overline{\text{DRACK2}}$ / $\overline{\text{DONE2}}$
J3	PC30 / EXT1 / BRG20 / CLK2 / $\overline{\text{TOUT1}}$
J4	V_{DD}
J5	GND
J6	GND
J7	PA30 / FCC1:UTOP1A8:TXCLAV / FCC1:UTOP1A8:TXCLAV0 / FCC1:MII:CRS / FCC1:HDLC and transparent:RTS
J13	$\overline{\text{TA}}$
J14	GND
J15	V_{DDH}

Table 3-2. MSC8103 Signal Listing by Pin Designator (Continued)

Number	Signal Name
J16	V_{DDH}
J17	PSDAMUX / PGPL5
J18	\overline{PGTA} / PUPMWAIT / \overline{PPBS} / PGPL4
J19	$\overline{PWE3}$ / $\overline{PSDDQM3}$ / $\overline{PBS3}$
K1	PA28 / FCC1:UTOPIA8:RXENB / FCC1:MII:TX_EN
K2	PD29 / FCC1:UTOPIA8:RXADDR3 / FCC1:UTOPIA8:RXCLAV2 / SCC1:RTS/TENA
K3	PC29 / SCC1: \overline{CTS} / SCC1:CLSN / BRG30 / CLK3 / TIN2
K4	PB29 / FCC2:MII:TX_EN / TDMB2:L1RSYNC
K5	V_{DDH}
K6	GND
K7	GND
K13	GND
K14	$\overline{PWE2}$ / $\overline{PSDDQM2}$ / $\overline{PBS2}$
K15	GND
K16	V_{DDH}
K17	$\overline{PWE1}$ / $\overline{PSDDQM1}$ / $\overline{PBS1}$
K18	$\overline{PWE0}$ / $\overline{PSDDQM0}$ / $\overline{PBS0}$
K19	$\overline{CS2}$
L1	PA27 / FCC1:UTOPIA8:RXSOC / FCC1:MII:RX_DV
L2	PB28 / FCC2:RX_ER / FCC2:HDLC: \overline{RTS} / SCC2: \overline{RTS} /TENA / TDMB2:L1TSYNC
L3	PC28 / SCC2: \overline{CTS} /CLSN / BRG40 / CLK4 / TIN1/ $\overline{TOUT2}$
L4	V_{DD}
L5	GND
L6	GND
L7	PC27 / CLK5 / BRG50 / $\overline{TGATE2}$
L13	$\overline{CS6}$
L14	GND
L15	GND
L16	V_{DD}
L17	$\overline{CS1}$
L18	$\overline{CS3}$
L19	$\overline{BCTL1}$
M1	PB27 / FCC2:MII:COL / TDMC2:L1TXD
M2	PC26 / TMCLK / BRG60 / CLK6 / $\overline{TOUT3}$
M3	PB26 / FCC2:MII:CRS / TDMC2:L1RXD
M4	V_{DDH}
M5	GND
M6	PA26 / FCC1:UTOPIA8:RXCLAV / FCC1:UTOPIA8:RXCLAV0 / FCC1:MII:RX_ER

GND_{SYN} and GND_{SYN1} should be provided with an extremely low impedance path to ground and should be bypassed to V_{CCSYN} and V_{CCSYN1} , respectively, by a 0.01- μF capacitor located as close as possible to the chip package. The user should also bypass GND_{SYN} and GND_{SYN1} to V_{CCSYN} and V_{CCSYN1} with a 0.01- μF capacitor as closely as possible to the chip package

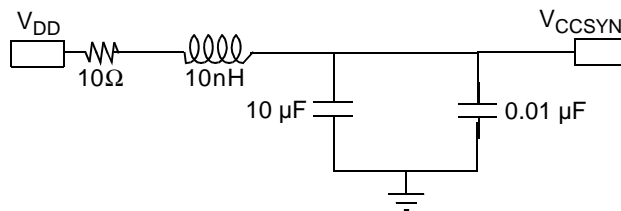


Figure 4-2. V_{CCSYN} and V_{CCSYN1} Bypass

